

**IN THE ABSTRACT OF THE DISCLOSURE**

Please amend the Abstract as follows:

~~Disclosed is a~~ A method and apparatus for coating liquid films on to the surface of a wafer substrate by rotation the substrate at a speed sufficient to cause a liquid, through centrifugal effect, to flow outwardly toward the perimeter of the surface and form a substantially uniform thickness liquid coating thereon, and starting from one edge at the central region of the wafer surface and moving radially outward therefrom in a single direction, spraying a fine mist of the liquid to the surface of the wafer.